

ESDALC6V1W5

Quad TRANSIL™ array for data protection

Main applications

Where transient overvoltage protection in ESD sensitive equipment is required, such as :

- Computers
- Printers
- Communication systems
- Cellular phones and accessories
- Wireline and wireless telephone sets
- Set top boxes

Features

- 4 Unidirectional Transil functions
- Breakdown voltage:V_{BR} = 6.1 V minimum
- Low leakage current: < 1 µA
- Low capacitance: 7.5 pF at 3 V
- Very small PCB area < 4.2 mm² typically

Description

The ESDALCxxxWx are monolithic suppressors designed to protect components connected to data and transmission lines against ESD.

These devices clamp the voltage just above the logic level supply for positive transients, and to a diode drop below ground for negative transients.

Benefits

January 2006

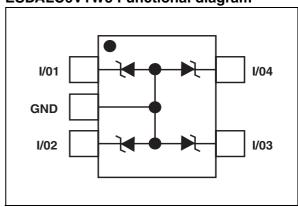
- High ESD protection level: up to 25 kV
- High integration



Order codes

Part Number	Marking		
ESDALC6V1W5	C61		

ESDALC6V1W5 Functional diagram



Complies with the following standards

IEC61000-4-2

Level 4 15 kV (air discharge)

8 kV(contact discharge)

MIL STD 883E - Method 3015-7 Class 3

25 kV HBM (Human Body Model)

TM: TRANSIL is a trademark of STMicroelectronics

Rev 5

1/7

1 Characteristics ESDALC6V1W5

1 Characteristics

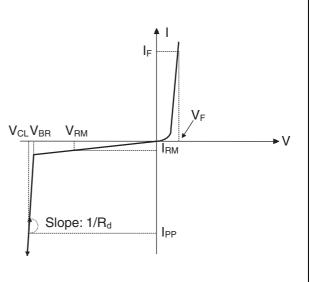
Table 1. Absolute Ratings ($T_{amb} = 25^{\circ}C$)

Symbol	Parameter	Value	Unit
P _{PP}	Peak pulse power (8/20 μs)	25	W
Tj	Junction temperature	150	°C
T _{stg}	Storage temperature range	-55 to +150	°C
TL	Maximum lead temperature for soldering during 10s	260	°C
T _{op}	Operating temperature range ⁽¹⁾	-40 to +150	°C

^{1.} The values of the operating parameters versus temperature are given through curves and αT parameter.

1.1 Electrical Characteristics (Tamb = 25°C)

Symbol	Parameter		
V _{RM}	Stand-off voltage		
V_{BR}	Breakdown voltage		
V _{CL}	Clamping voltage		
I _{RM}	Leakage current		
I _{PP}	Peak pulse current		
I _R	Reverse leakage current		
I _F	Forward current		
αΤ	Voltage temperature coefficient		
V_{F}	Forward voltage drop		
С	Capacitance		
R _d	Dynamic resistance		



	V _{BR} @ I _R		I _{RM} @ V _{RM}		R _d	αΤ	С	
Part Numbers	min.	max.		max.		typ. ⁽¹⁾	max. ⁽²⁾	typ. 3V bias
	V	V	mA	μΑ	V	Ω	10 ⁻⁴ /°C	pF
ESDALC6V1W5	6.1	7.2	1	1	3	1.1	6	7.5

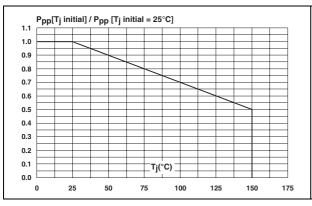
^{1.} Square pulse I_{pp} = 15 A, t_p = 2.5 μs

^{2.} $V_{BR} = aT^* (T_{amb} - 25 °C) * V_{BR} (25 °C)$

ESDALC6V1W5 1 Characteristics

Figure 1. Peak power dissipation versus initial junction temperature

Figure 2. Peak pulse power versus exponential pulse duration (T_i initial = 25°C)



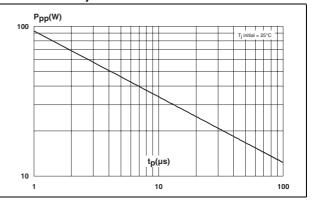
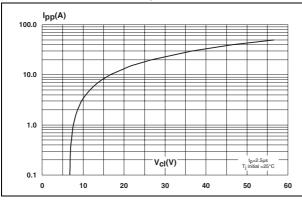


Figure 3. Clamping voltage versus peak pulse Figure 4. current (T_j initial = 25°C, rectangular waveform, t_p = 2.5 μ s)

Capacitance versus reverse applied voltage (typical values)



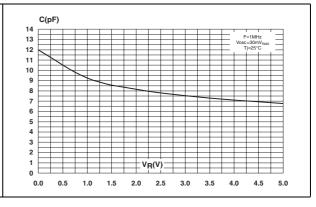
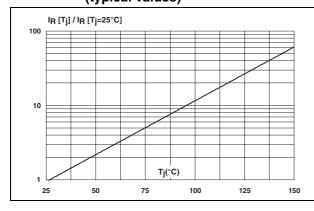


Figure 5. Relative variation of leakage current Figure 6. versus junction temperature (typical values)

Peak forward voltage drop versus peak forward current (typical values)



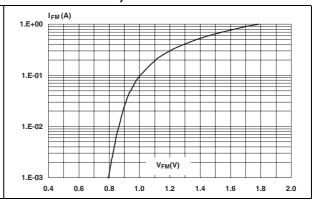
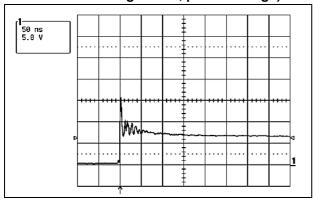
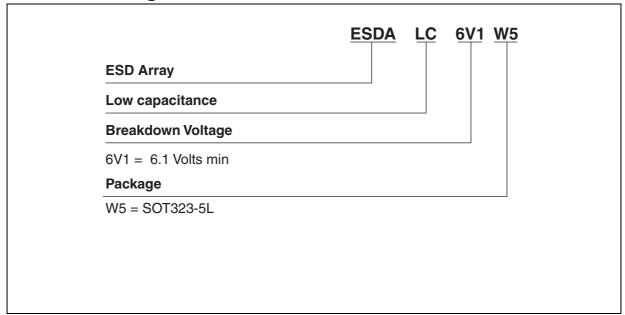


Figure 7. ESD response to IEC61000-4-2 (air discharge 15 kV, positive surge)



2 Ordering information scheme



3 Package mechanical data

3.1 SOT323-5L package

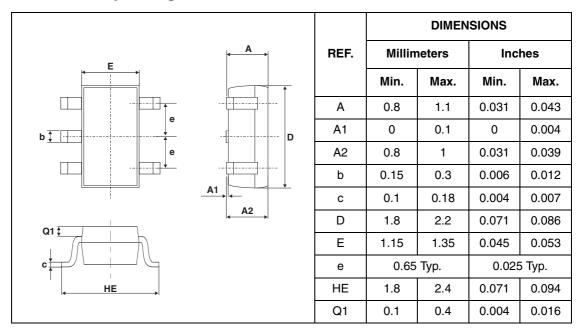
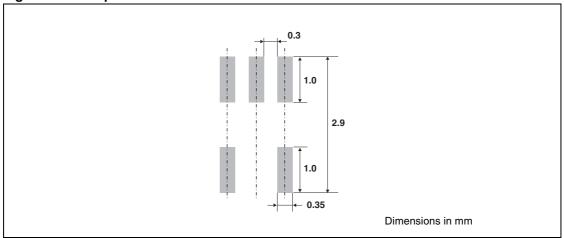


Figure 8. Footprint dimensions



In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect . The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com.

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4 Ordering information ESDALC6V1W5

4 Ordering information

Part Number	Marking	Package	Weight	Base qty	Delivery mode
ESDALC6V1W5	C61	SOT323-5L	5.4 mg	3000	Tape & reel

5 Revision history

Date	Revision	Changes
Jun-2002	4A	Previous issue
10-Jan-2006	5	Reformatted to current template. Figure 5: Range of T _j extended to 150 °C. Figure 6: Peak forward voltage drop versus peak forward current (typical values) added.

ESDALC6V1W5 5 Revision history

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